2SK2211

Silicon N-Channel MOS FET

For switching

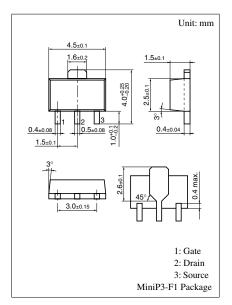
■ Features

- Low ON-resistance R_{DS(on)}
- High-speed switching
- Mini-power type package, allowing downsizing of the sets and automatic insertion through the tape/magazine packing.

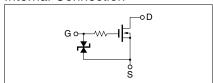
■ Absolute Maximum Ratings (Ta = 25°C)

Parameter	Symbol	Ratings	Unit	
Drain to Source breakdown voltage	V _{DSS}	30	V	
Gate to Source voltage	V _{GSS}	±20	V	
Drain current	I_D	1.0	A	
Max drain current	I_{DP}	2.0	A	
Allowable power dissipation	P _D *	1.0	W	
Channel temperature	T _{ch}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	

^{*} PC board: Copper foil of the drain portion should have a area of 1cm² or more and the board thickness should be 1.7mm.



Marking Symbol: 2M Internal Connection



■ Electrical Characteristics (Ta = 25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	I_{DSS}	$V_{DS} = 25V, V_{GS} = 0$			10	μA
Gate to Source leakage current	I_{GSS}	$V_{GS} = \pm 15V, V_{DS} = 0$			±10	μA
Drain to Source breakdown voltage	V _{DSS}	$I_D = 0.1 \text{mA}, \ V_{GS} = 0$	30			V
Gate to Source voltage	V _{GSS}	$I_{GS} = 0.1 \text{mA}, V_{DS} = 0$	±20			V
Gate threshold voltage	V _{th}	$V_{DS} = 5V$, $I_D = 1mA$	0.8		2.0	V
Drain to Source Oly-resistance =	R _{DS(on)1} *1	$V_{GS} = 4V, I_D = 0.5A$		0.48	0.75	Ω
	R _{DS(on)2} *1	$V_{GS} = 10V, I_D = 0.5A$		0.35	0.60	Ω
Forward transfer admittance	Y _{fs} *1	$V_{DS} = 10V, I_D = 0.5A$	0.5			S
Input capacitance (Common Source)	C _{iss}			87		pF
Output capacitance (Common Source)	Coss	$V_{DS} = 10V, V_{GS} = 0, f = 1MHz$		69		pF
Reverse transfer capacitance (Common Source)	C _{rss}			23		pF
Turn-on time (delay time)	t _{d(on)}	$V_{GS} = 10V, I_D = 0.5A$ $V_{DD} = 10V, R_I = 20\Omega$		12		ns
Fall time	t _f			160		ns
Turn-off time (delay time)	t _{d(off)}	$\mathbf{v}_{\mathrm{DD}} = 10 \mathbf{v}, \mathbf{K}_{\mathrm{L}} = 2022$		60		ns

^{*1} Pulse measurement

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